

(1,00mm) .03937"

MEC1 SERIES

MEC1-120-02-F-D-A

MEC1-130-02-F-D-A

MEC1-140-02-L-D

# MINI EDGE CARD SOCKET

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?MEC1](http://www.samtec.com?MEC1)

**Insulator Material:**

Black LCP

**Contact Material:**

BeCu

**Plating:**

Sn or Au over 50µ"

(1,27µm) Ni

**Operating Temp Range:**

-55°C to +125°C

**Current Rating:**

2A @ 80°C ambient

(See website for details)

**Voltage Rating:**

300 VAC

**Insertion Depth:**

(5,84mm) .230" to

(8,13mm) .320"

**RoHS Compliant:**

Yes

**Processing:**

**Lead-Free Solderable:**

Yes

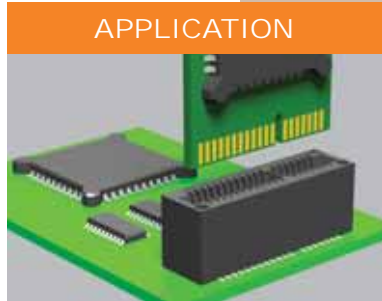
**SMT Lead Coplanarity:**

(0,10mm) .004" max (05-20)

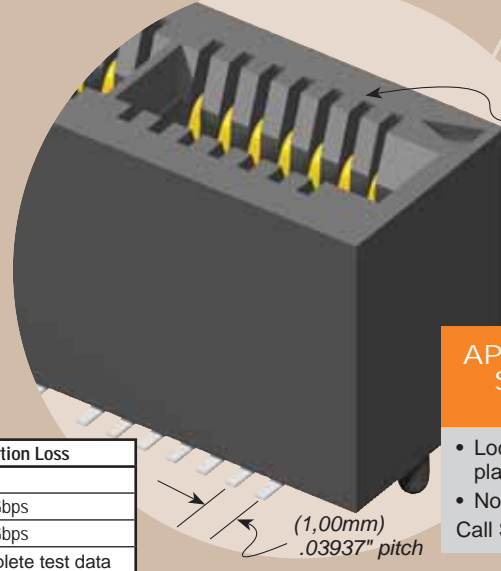
(0,15mm) .006" max (30-70)



**Mates with:**  
(1,60mm) .062" card



## APPLICATION



Mates with  
(1,60mm)  
.062" card

## APPLICATION SPECIFIC OPTION

- Locking Clip (Manual placement required).
- Non-polarized  
Call Samtec.

1mm MEC1	Rated @ -3dB Insertion Loss
<b>9,19mm Stack Height</b>	
Single-Ended Signaling	5.5 GHz / 11 Gbps
Differential Pair Signaling	6.5 GHz / 13 Gbps

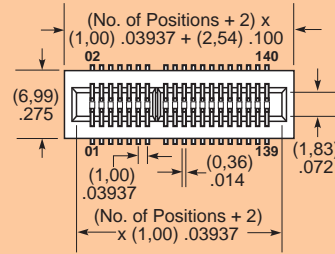
Performance data for other stack heights and complete test data available at [www.samtec.com?MEC1](http://www.samtec.com?MEC1) or contact [sig@samtec.com](mailto:sig@samtec.com)



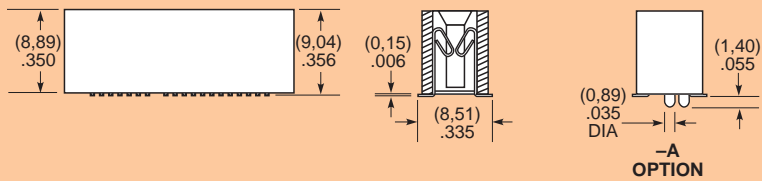
05, 08, 20, 30, 40, 50, 60, 70

- F = Gold flash on contact, Matte tin on tail
- L = 10µ" (0,25µm) Gold on contact, Matte Tin on tail

- A = Alignment Pin metal or plastic at Samtec discretion.
- K = (7,87mm) .310" DIA Polyimide film Pick & Place Pad
- TR = Tape & Reel



POSITIONS PER ROW	POLARIZED POSITIONS (No Contact)
05	3, 4
08	5, 6
20	15, 16
30	21, 22
40	31, 32
50	41, 42
60	31, 32, 63 & 64
70	53, 54, 115 & 116



**Note:** Other Gold plating options available. Contact Samtec.

**Note:** Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)